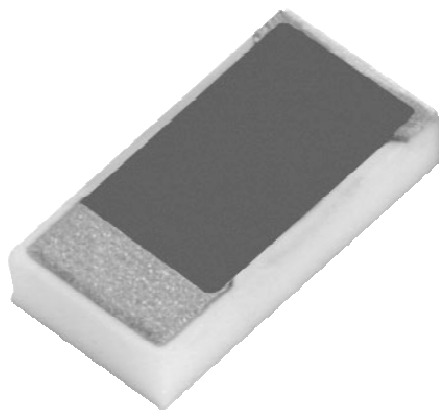


### Chip Termination 30 Watts, 50Ω



#### General Specifications

Resistive Element	Thick film
Substrate	Beryllium oxide ceramic
Terminals	Thick film silver

#### Electrical Specifications

Resistance Range:	50 ohms, $\pm 2\%$
Frequency Range;	DC – 3.0 GHz
Power:	30 Watts
VSWR	1.25:1 DC – 3.0 GHz

**Note:** Tolerance is  $\pm 0.010"$ , unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is  $-55^{\circ}\text{C}$  to  $150^{\circ}\text{C}$  (see chart for derating temperatures).

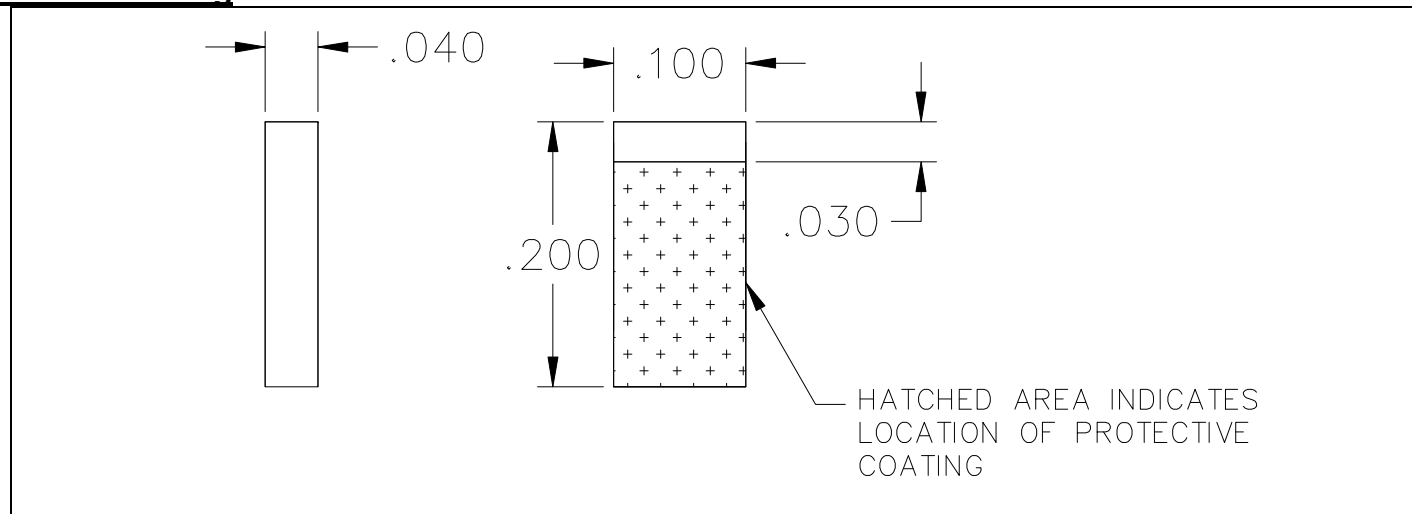
All dimensions in inches.

Specifications subject to change without notice.

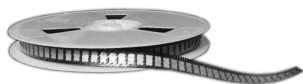
#### Features:

- DC – 3.0 GHz
- 30 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

#### Outline Drawing

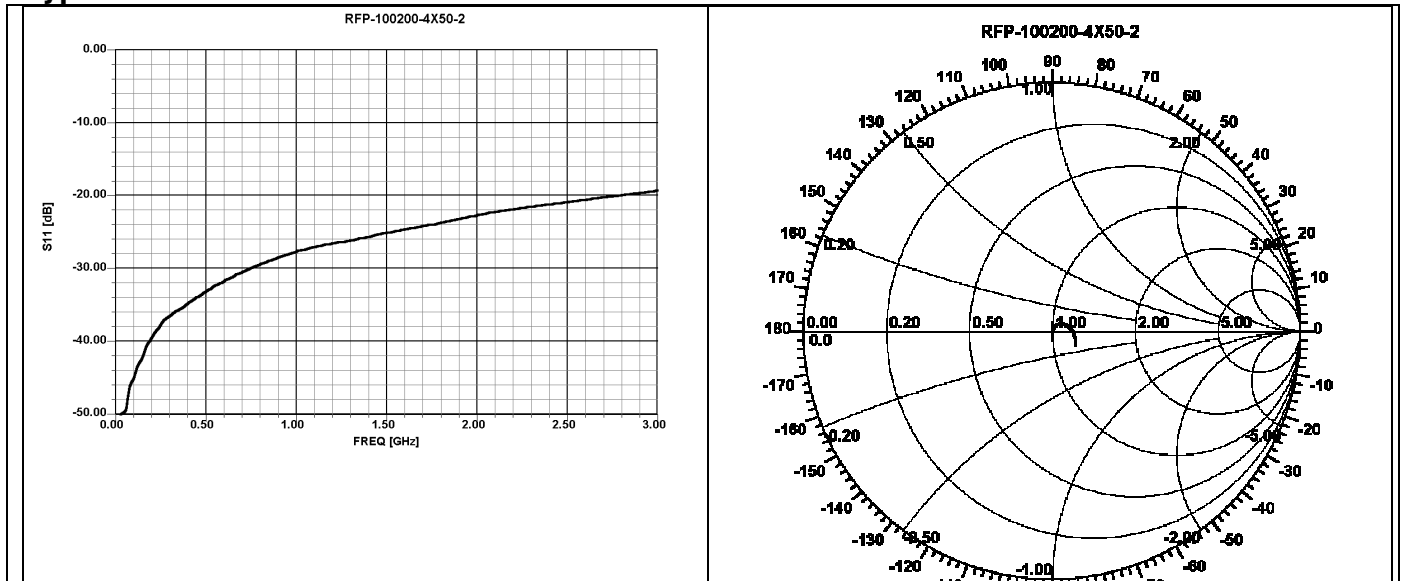


100200-4X50-2 (097) Rev A

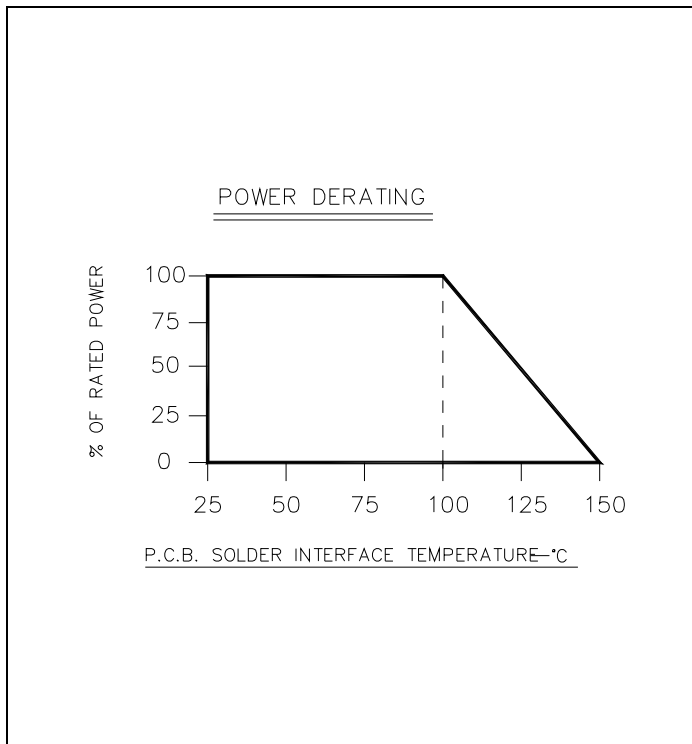




## Typical Performance:



## Power De-rating:



## Mounting Footprint and Procedure:

**SUGGESTED STRESS RELIEF METHODS**  
SCALE: NONE

**NOT RECOMMENDED APPLICATION**  
SCALE: NONE

**SUGGESTED MOUNTING PROCEDURES:**

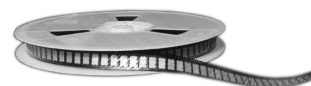
1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPRIATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

\*\* FOR MORE DETAILS CONTACT FACTORY \*\*

100200-4X50-2 (097) Rev A

USA/Canada: (315) 432-8909  
Toll Free: (800) 544-2414  
Europe: +44 2392-232392

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Reel For Pick and Place  
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